



Material Content Data Sheet



Sales Product Name		ICE3RBR0665JZ		Issued		26. September 2017		
MA#		MA001127144						
Package		PG-DIP-7-4		Weight*		653.13 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.709	0.87	0.87	8741	8741
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.01		74	
	non noble metal	zinc	7440-66-6	0.194	0.03		297	
	non noble metal	iron	7439-89-6	3.884	0.59		5948	
wire	non noble metal	copper	7440-50-8	157.726	24.15	24.78	241493	247812
	noble metal	gold	7440-57-5	0.283	0.04	0.04	434	434
	encapsulation	organic material	carbon black	1333-86-4	1.424	0.22		2180
encapsulation	plastics	epoxy resin	-	46.044	7.05		70497	
	inorganic material	silicondioxide	60676-86-0	427.211	65.42	72.69	654102	726779
leadfinish	non noble metal	tin	7440-31-5	6.460	0.99	0.99	9890	9890
plating	noble metal	silver	7440-22-4	1.911	0.29	0.29	2926	2926
glue	plastics	epoxy resin	-	0.335	0.05		513	
	noble metal	silver	7440-22-4	1.898	0.29	0.34	2905	3418
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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